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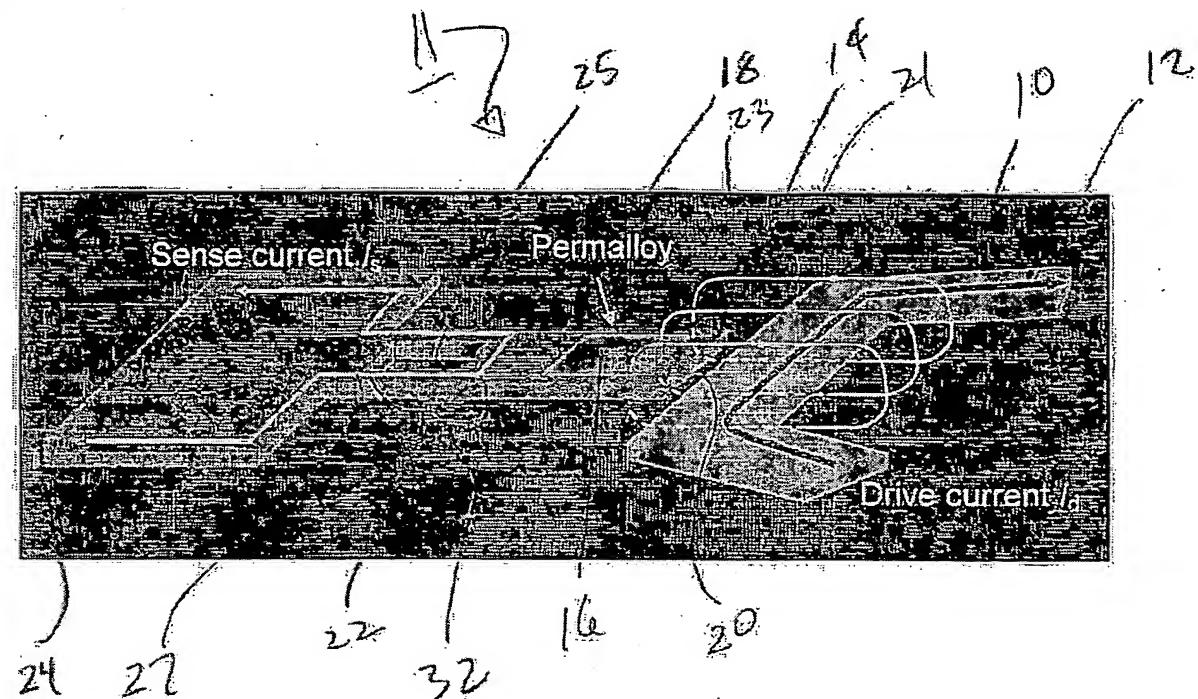
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Fig. 1



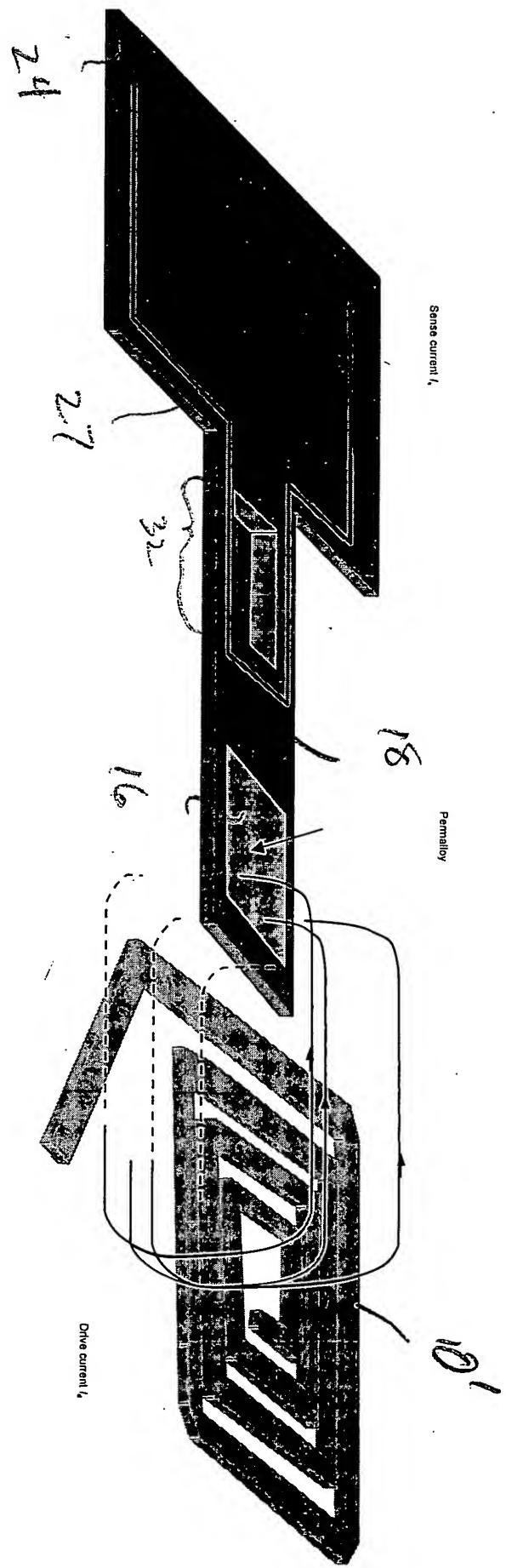


Fig. 2

Fig. B
2

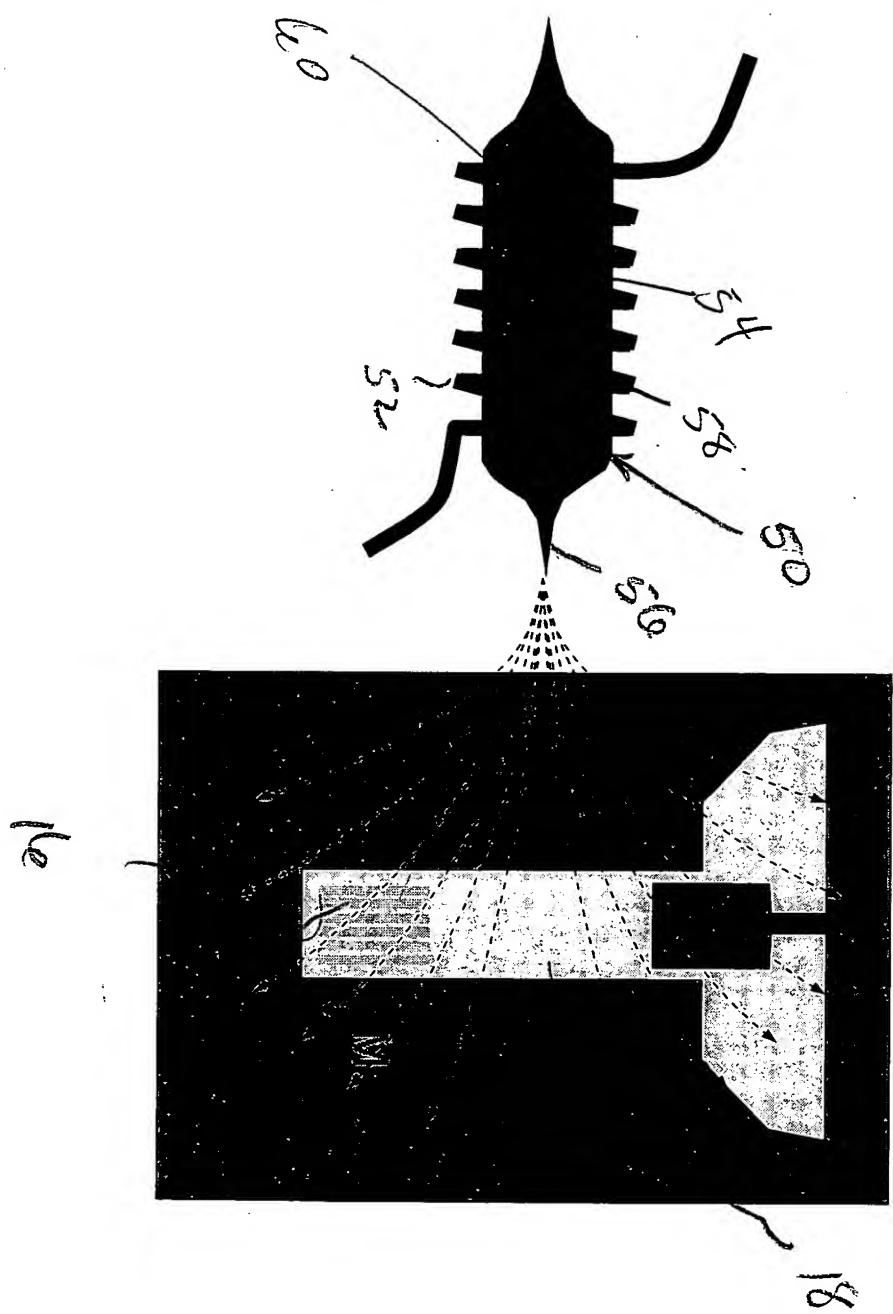


Fig. 4 (a)

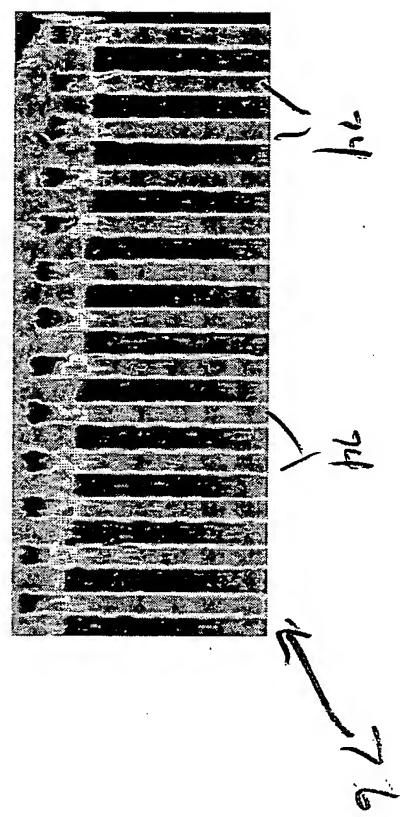
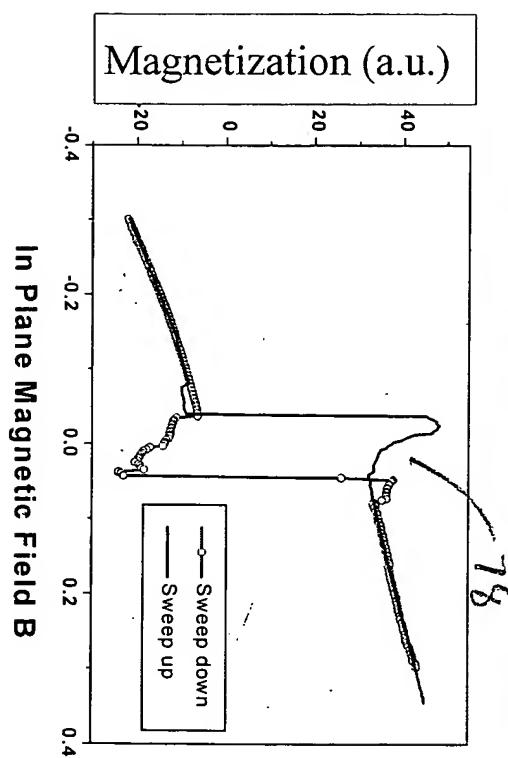
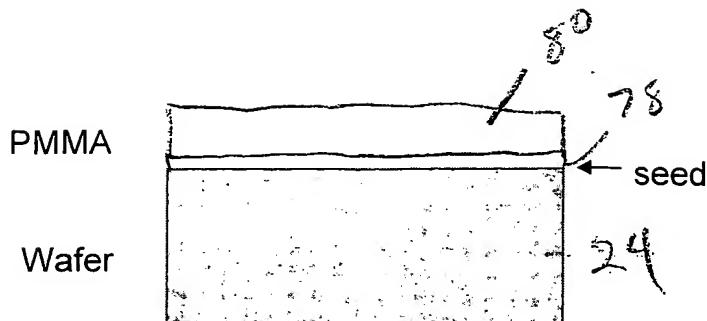
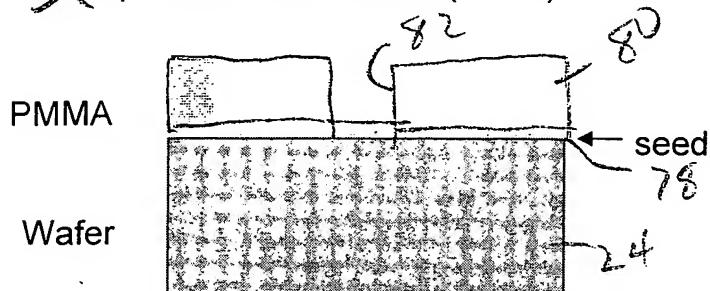


Fig. 4 (b)

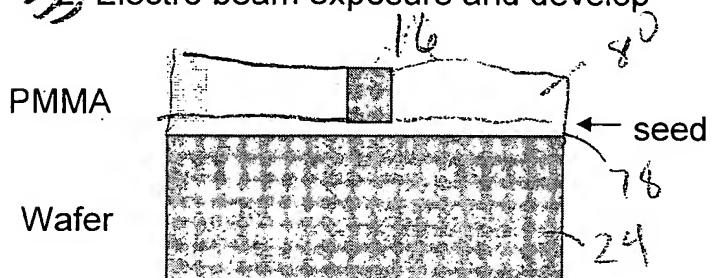




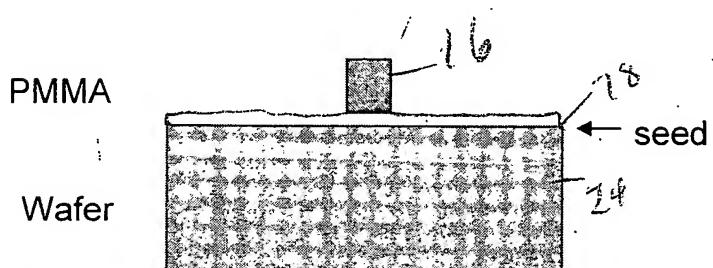
5.1 Spin coat thick PMMA (~2um)



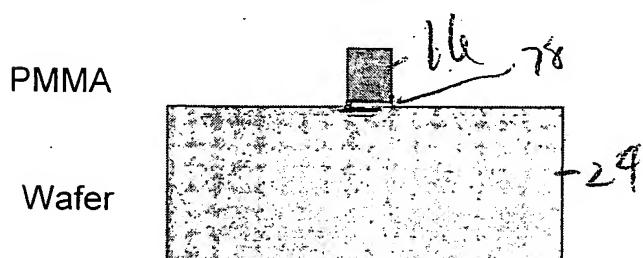
5.2 Electro beam exposure and develop



5.3 Electro beam exposure and develop



5.4 Stripe off PMMA



5.5 Dry etch seed metal layer

Fig 5f 11c

CIT 43 KU X2 5 9 8 7 6 5 4 3 2 1 11m

Fig. 6a



Cu or coating 30 nm

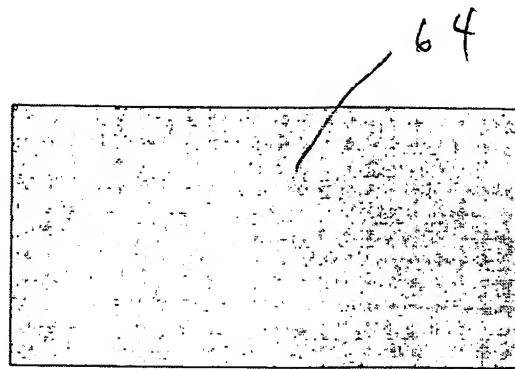
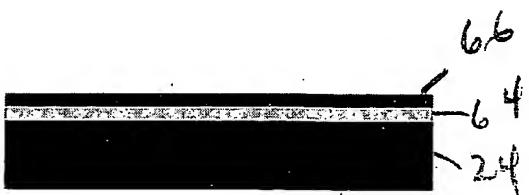


Fig. 6b



Insulator deposition 1um
SiN or cured photoresist

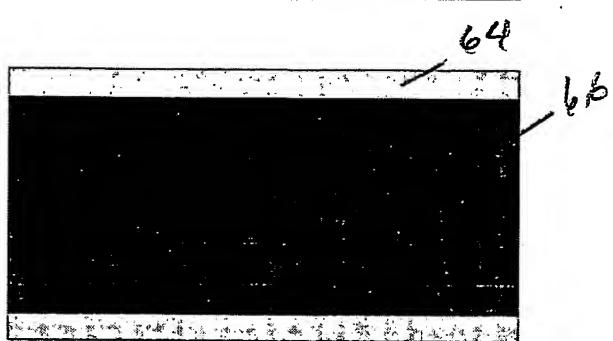
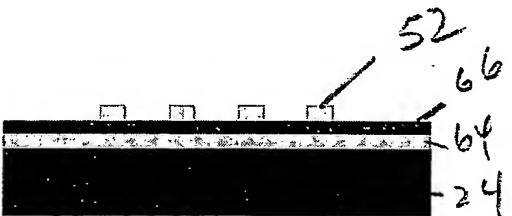


Fig. 6c



Bottom conductor
Plating, Cu or Au 1um

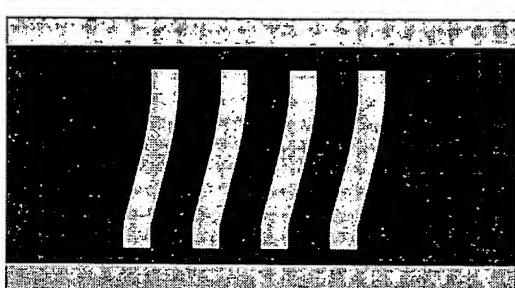
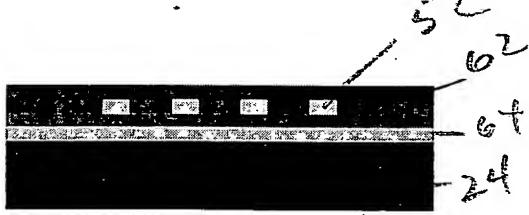


Fig. 6d



1um Cured Photoresist
Or PECVD SiO2

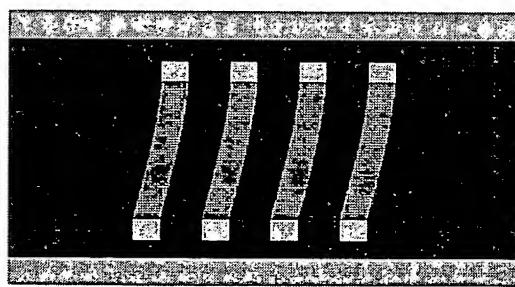
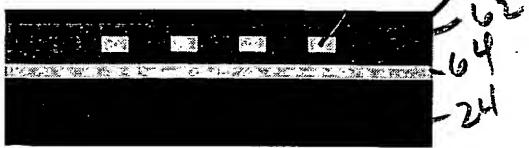
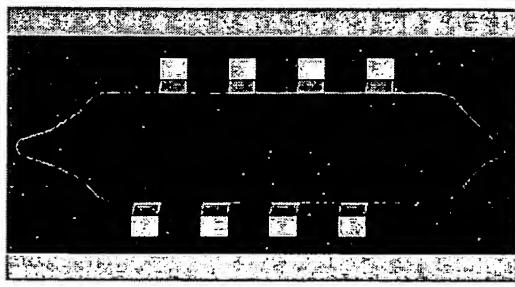


Fig. 6e



Electroplate 1um Ni core



54
56

Fig. 6F

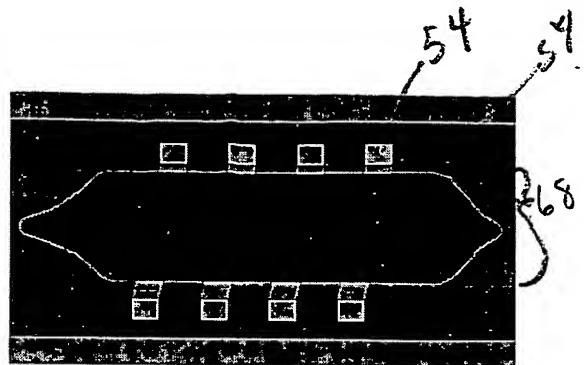
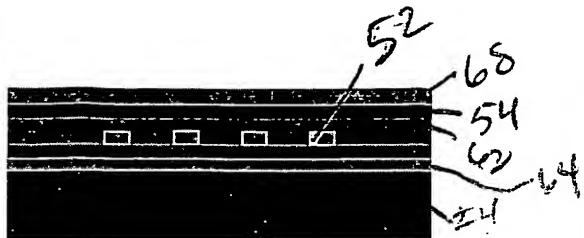


Fig. 6G

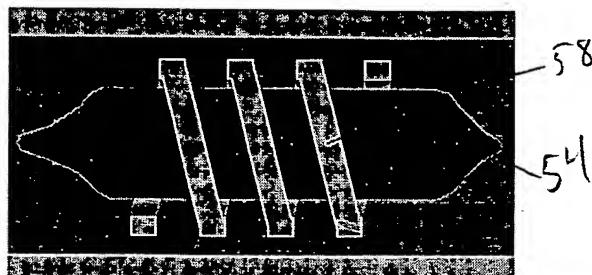
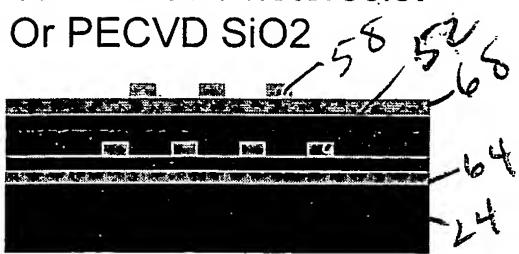


Fig. 6H

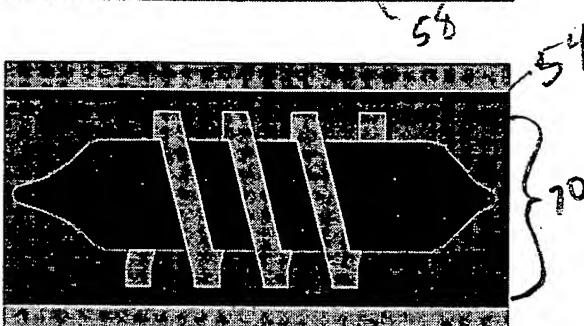
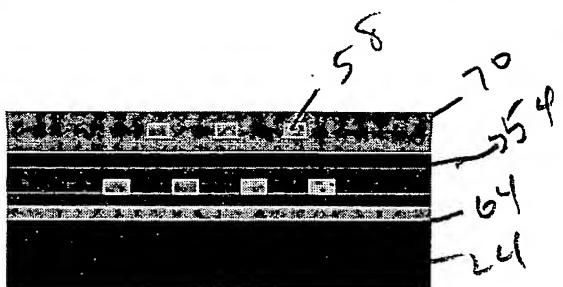


Fig. 6I

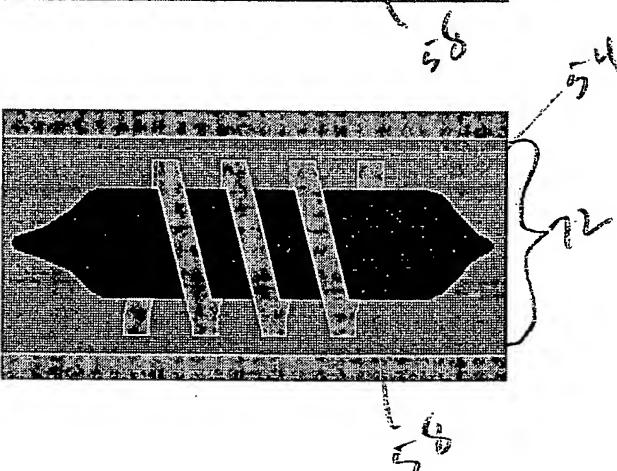
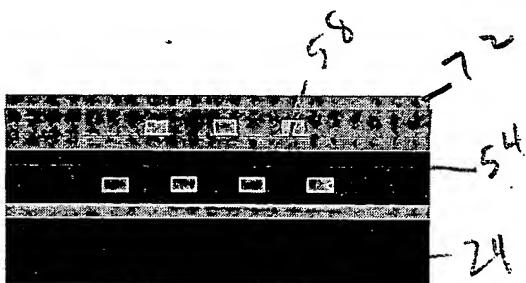


Fig. 7

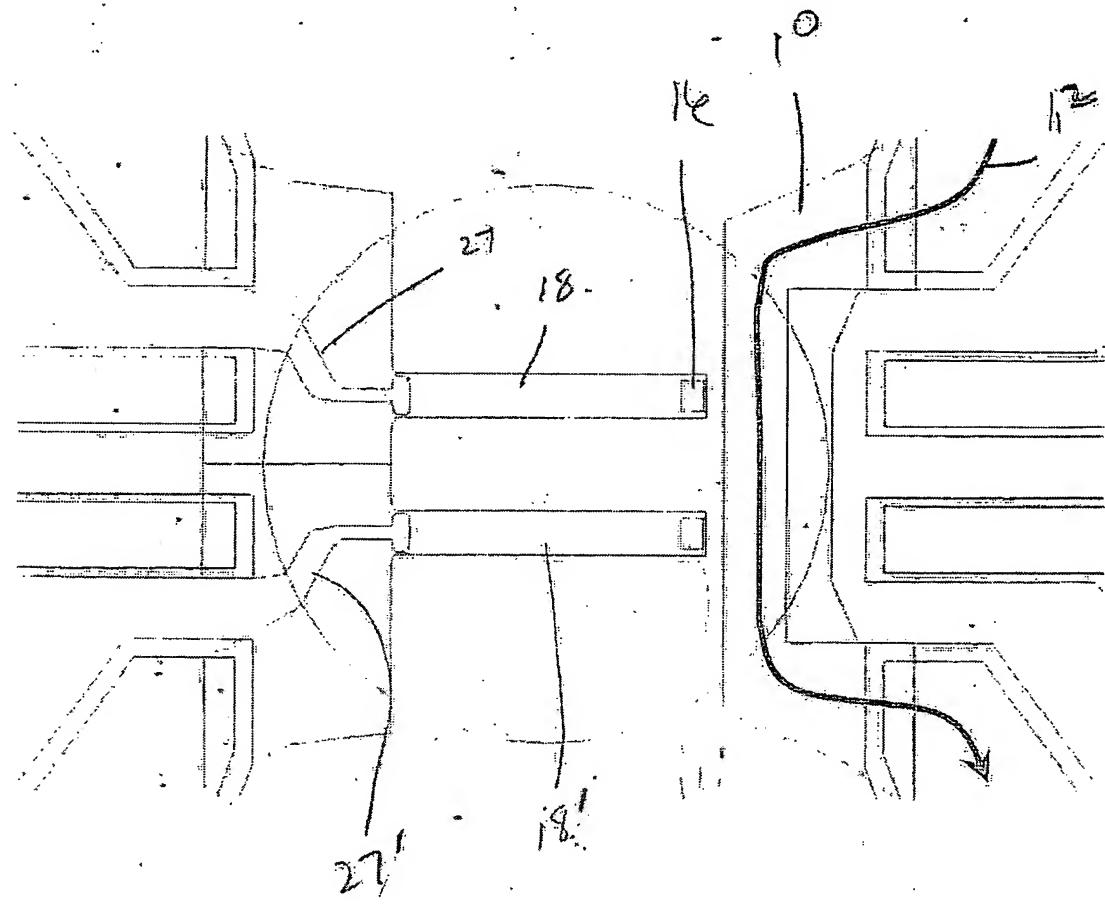


Fig. 8

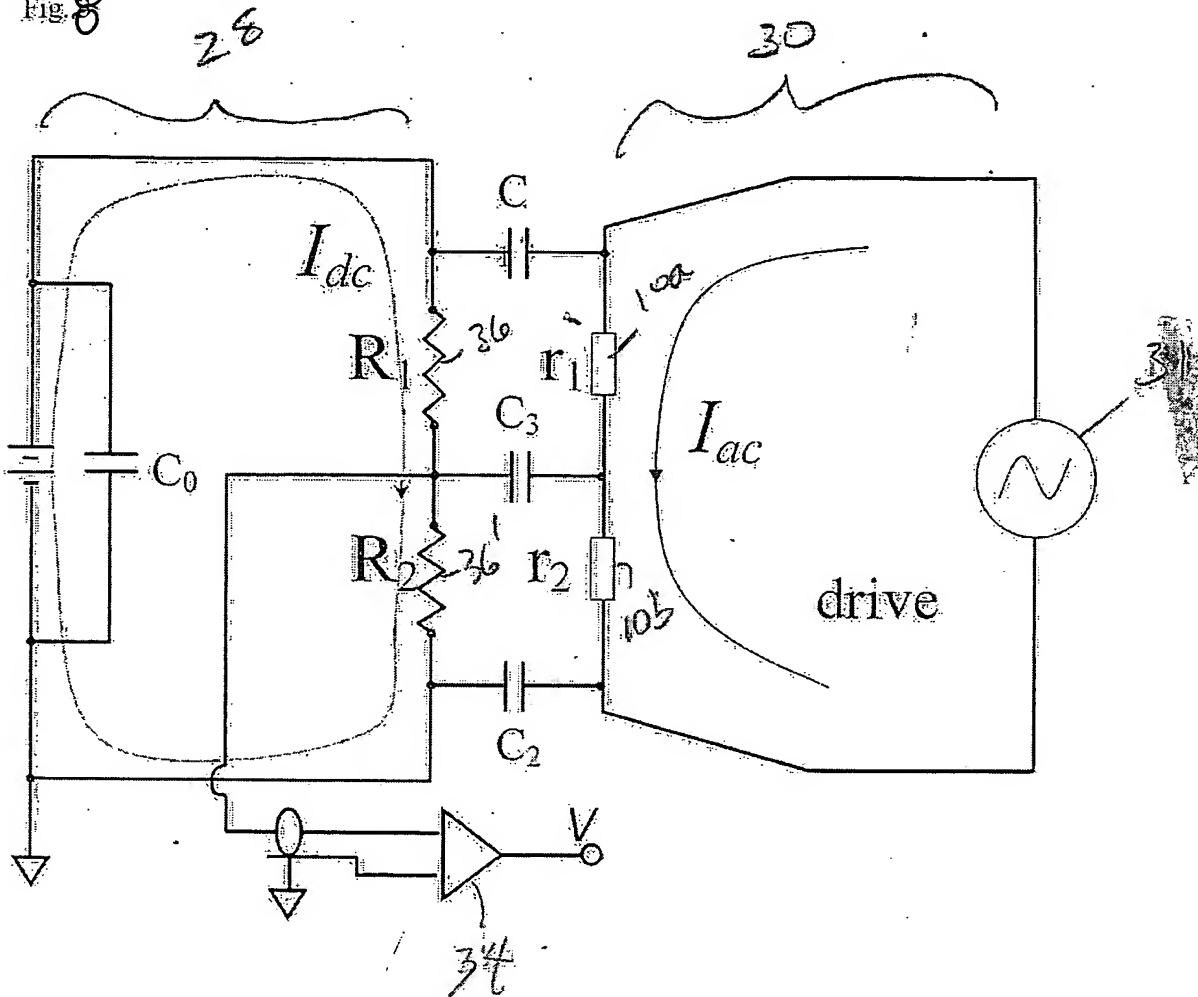


Fig 9a

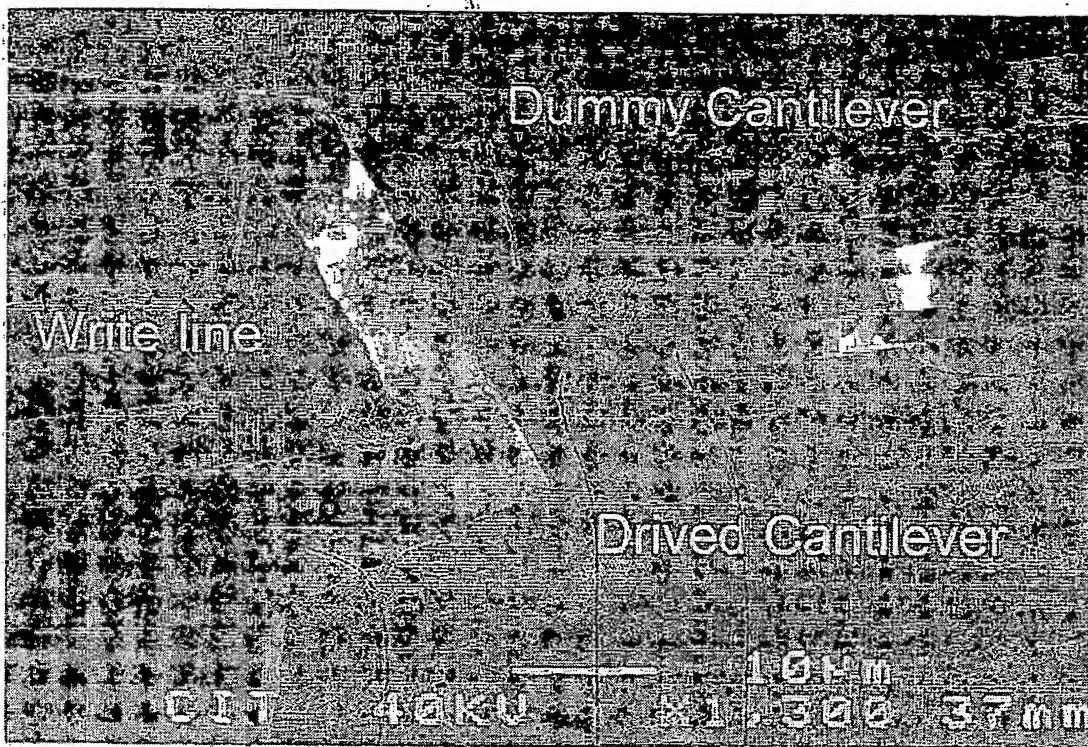


Fig. 9b

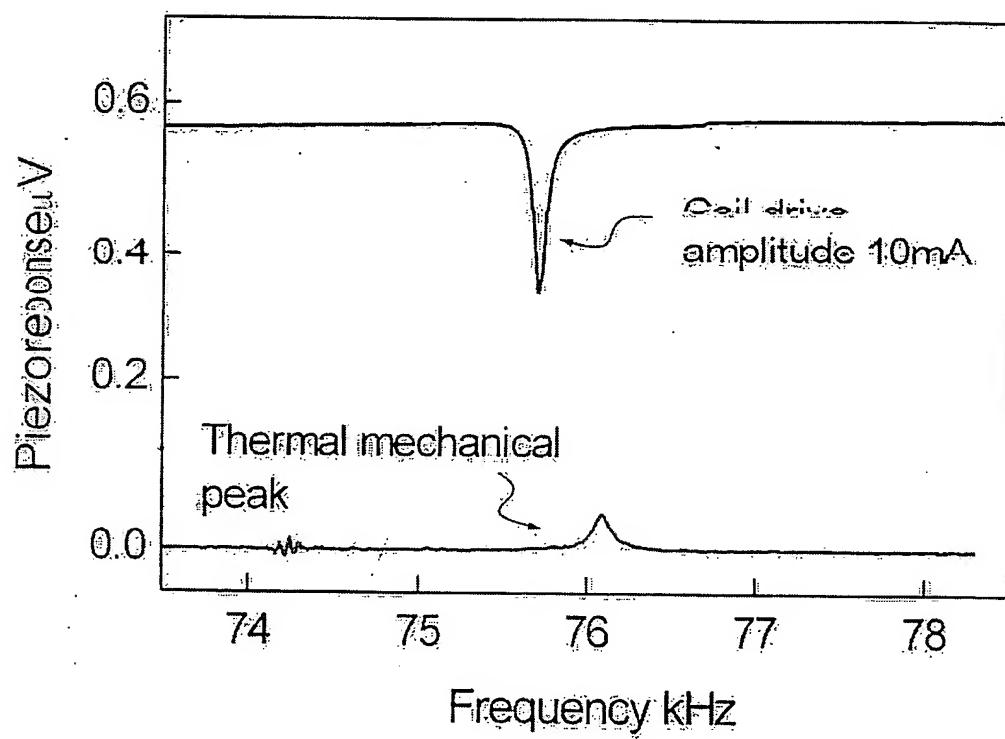


Fig. 10

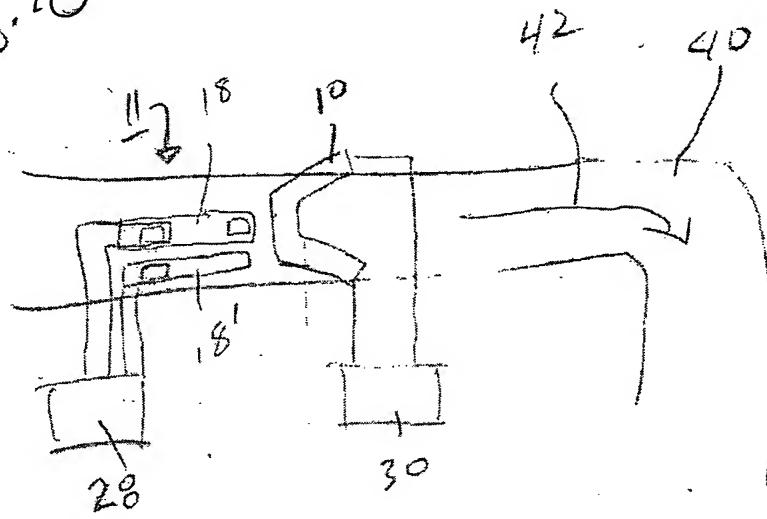


Fig. 11

